L Number	Hits	Search Text	DB	Time stamp
3	0	("863030.ap.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 11:23
4	3	863030.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 11:46
5	2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:04
6	0	("MMIC.ti,ab,clm. and thick adj film adj capacitor").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:04
7	1	MMIC.ti,ab,clm. and thick adj film adj capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:11
8	0	MMIC.ti,ab,clm. and air near2 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:12
9	0	MMIC.ti,ab,clm. and (spacing or air) near2 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:13
10	0	MMIC same (spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:15
11	13	(spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:16
12	0	(spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver) and (257/$6.ccls. or 438/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:17
13	2	(spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver) and (257/$6.ccls. or 438/$6.ccls. or 455/$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:19
14	13	(spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 17:05
15	2	488721.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:12

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16	37	LTCC and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:13
17	0	LTCC near12 transfer adj tape and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:13
18	4	LTCC and transfer adj tape and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:18
19	4	LTCC and transfer adj tape and (monolithic adj microwave adj integrated adj circuit or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:20
20	7	(low adj temperature adj co-fired adj ceramic or LTCC) and transfer adj tape and (monolithic adj microwave adj integrated adj circuit or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 14:43
21	170	MMIC.ti,ab,clm. and capacitor same resistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 14:44
22	73	MMIC.ti,ab,clm. and capacitor same resistor.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 14:44
23	5	MMIC.ti,ab,clm. and capacitor same resistor.ti,ab,clm. and transceiver.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 14:45
24	1427	((257/277) or (257/728) or (455/73)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 17:07
25	81	(((257/277) or (257/728) or (455/73)).CCLS.) and (mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 17:10
26	8	(((257/277) or (257/728) or (455/73)).CCLS.) and (mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm. and transceiver	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 17:10
–	0	mmic.ti. and transceiver.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:25
–	15	mmic.ti. and transceiver	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:12
–	1	mmic.ti. and transceiver and (tuned or tuning)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:13

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-	0	mmic.ti. and transceiver.ti,ab,clm. and (tuned or tuning).ti,ab.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:15
-	2	(mmic or microwave adj monolithic).ti. and transceiver.ti,ab,clm. and (tuned or tuning).ti,ab.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:44
-	0	(mmic or microwave adj monolithic).ti. and transceiver.ti,ab,clm. and 438/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:44
-	20	(mmic or microwave adj monolithic).ti. and 438/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/14 14:44
-	370	integrated adj circuit adj board.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/17 12:07
-	7	integrated adj circuit adj board.ti. and integrated adj circuit adj board.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/17 12:08
-	634	(455/73).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:25
-	147	(257/277).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:25
-	551	(257/728).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:26
-	1978	(mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:26
-	1325	((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:27
-	70	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) and (((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:27
-	3233	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or (((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:27
-	221	(((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or (((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))) and transceiver.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:28

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-	4	((((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or (((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.))) and transceiver.ti,ab,clm.) and transfer adj tape	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:29
-	2	("5545924").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 17:13
-	2	("6124636").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 17:14
-	13	"5423080"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 17:14
-	2	("5423080").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 17:14
-	18	(US-5423080-$ or US-6124636-$ or US-6424074-$ or US-6124765-$ or US-6278337-$ or US-6278159-$ or US-5545924-$ or US-6268779-$ or US-6073484-$ or US-6441449-$ or US-6201728-$ or US-6257058-$).did. or (US-20010001224-$).did. or (EP-712534-$ or EP-504020-$ or JP-11214578-$ or WO-200075762-$ or WO-200223674-$).did.	USPAT; US-PGPUB; DERWENT	2002/10/20 17:34
-	1	((US-5423080-$ or US-6124636-$ or US-6424074-$ or US-6124765-$ or US-6278337-$ or US-6278159-$ or US-5545924-$ or US-6268779-$ or US-6073484-$ or US-6441449-$ or US-6201728-$ or US-6257058-$).did. or (US-20010001224-$).did. or (EP-712534-$ or EP-504020-$ or JP-11214578-$ or WO-200075762-$ or WO-200223674-$).did.) and transfer adj tape	USPAT; US-PGPUB; DERWENT	2002/10/20 17:35
-	2724	mmic or monolithic adj microwave adj intergated adj circuit and transfer adj tape	USPAT; US-PGPUB; DERWENT	2002/10/20 17:35
-	5	(mmic or monolithic adj microwave adj integrated adj circuit) and transfer adj tape	USPAT; US-PGPUB; DERWENT	2002/10/20 17:36
-	19	(US-5451818-$ or US-6441449-$ or US-5423080-$ or US-6124636-$ or US-5545924-$ or US-6257058-$ or US-6278159-$ or US-6278337-$ or US-6201728-$ or US-6124765-$ or US-6424074-$ or US-6073484-$ or US-6268779-$).did. or (US-20010001224-$).did. or (EP-504020-$ or JP-11214578-$ or EP-712534-$ or WO-200223674-$ or WO-200075762-$).did.	USPAT; US-PGPUB; DERWENT	2002/10/20 19:33

–	8	((US-5451818-$ or US-6441449-$ or US-5423080-$ or US-6124636-$ or US-5545924-$ or US-6257058-$ or US-6278159-$ or US-6278337-$ or US-6201728-$ or US-6124765-$ or US-6424074-$ or US-6073484-$ or US-6268779-$).did. or (US-20010001224-$).did. or (EP-504020-$ or JP-11214578-$ or EP-712534-$ or WO-200223674-$ or WO-200075762-$).did.) and thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:05
–	18	(monolithic adj microwave or mmic).ti. and ((thick or thickness) same mil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:07
–	0	(monolithic adj microwave or mmic).ti. and ((thick or thickness) near12 mil near12 base)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:08
–	17	(monolithic adj microwave or mmic).ti. and ((thick or thickness) near12 mil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:12
–	25	cte near4 gaas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:50
–	2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:50
–	2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 07:56
–	0	("solder near3 MMIC adj chip").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 07:56
–	7	solder near3 MMIC adj chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:12
–	3	silver adj epoxy near6 MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:13
–	3	silver adj epoxy near12 chip and MMIC.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:14
–	5	silver adj epoxy near12 (die or chip) and (monolithic adj microwave or MMIC).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:15
–	6	silver adj epoxy near12 (die or chip) and (monolithic adj microwave or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:21

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-	16	solder near4 preform and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:21
-	13	solder near4 preform and MMIC.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:31
-	1	(radio-frequency or radio adj frequency or rf) adj (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:34
-	1	(radio-frequency or radio adj frequency or rf or kovar) adj (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:34
-	2	(radio-frequency or radio adj frequency or rf or kovar) near4 (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:03
-	158	isolation near3 (via or through-hole or through adj hole) and (chip or die).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:05
-	20	isolation adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:05
-	5	isolation adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:07
-	6	(insulation or isolation or insulating or isolating) adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:11
-	47	isolation adj via.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:12
-	1	isolation adj via.ti,ab,clm. and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:12
-	6	isolation adj via.ti,ab,clm. and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:17
-	1	(isolation adj via or isolation adj trench).ti,ab,clm. and (chip or die) and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:18
-	3097	mmic and sti or isolation adj trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:19

-	0	(isolation adj trench or sti) same mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:19
-	112	(isolation adj trench or sti) same chip and (integrated adj circuit or ic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:20
-	4	(isolation adj trench or sti) and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:31
-	12	epoxy near1 silver and integrated adj circuit and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:00
-	2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:01
-	2	("5319329").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:01
-	2	("5239685").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:01
-	2	("5406122").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:02
-	2	("5049978").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:02
-	2	("6426686").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:02